

(0.635 mm) .025"

DED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMSS

Insulator Material:

Liquid Crystal Polymer Terminal, Ground Plane & Shield Material: Phosphor Bronze Plating:

Au over 50 µ" (1.27 µm) Ni (Tin on Ground Plane Tail) Voltage Rating: 300 VAC mated with QFSS Operating Temp: -55 °C to +125 °C RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (026-078) **Board Stacking:**

For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

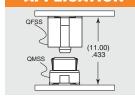
For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Headers without Alignment Pins
- 8 Power Pins/End
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- · Guide Post
- · Edge Mount
- 64 (-DP) and 104 pins per row

APPLICATION



Notes: Patented

Some lengths, styles and options are non-standard, non-returnable.

Board Mates:

Standoffs:



Integral metal plane for power or ground Increased insertion depth for rugged applications Optional Power Pins (1.30 mm) .051" NOMINAL WIPE Grounds to shield Sianal Pairs Differential routing

HIGH-SPEED CHANNEL PERFORMANCE

QMSS-DP/QFSS-DP @ 11 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

PINS PER ROW **QMSS** NO. OF PAIRS

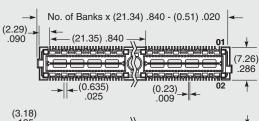
06.75

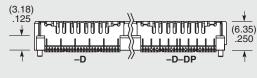
PLATING OPTION

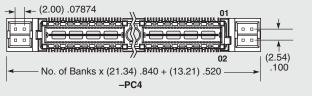
OTHER OPTION

-026, -052, -078 (52 total pins per bank 40 signals + 12 grounds to shield = -D)

–016, –032, –048 (16 pairs per bank = -D-DP)







= 10 µ" (0.25 µm) Gold on Signal Pins, Shield and **Ground Plane**

(Tin on Signal Pin tails, and Ground Plane tails)

(0.25)

010

(6.73)

.265

(2.31) .091

–D = Single-Ended -D-DP

= Differential Pair

_(6.35)

(2.54)

.100

= (5.50 mm) .217" DIA Polyimide film Pick & Place Pad (N/A with –PC4)

-PC4 = 4 Power Pins/End (N/A with -A)

OTHER SOLUTIONS



machined standoffs.

Due to technical progress, all designs, specifications and components are subject to change without notice